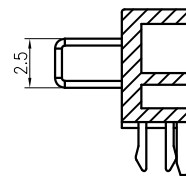
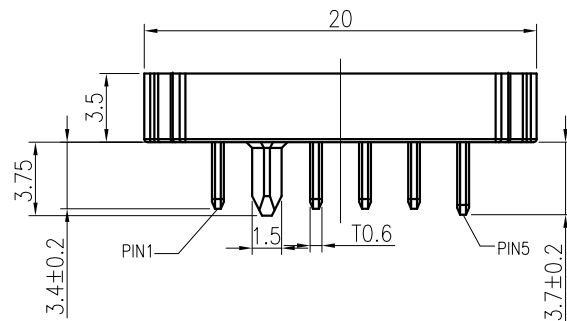


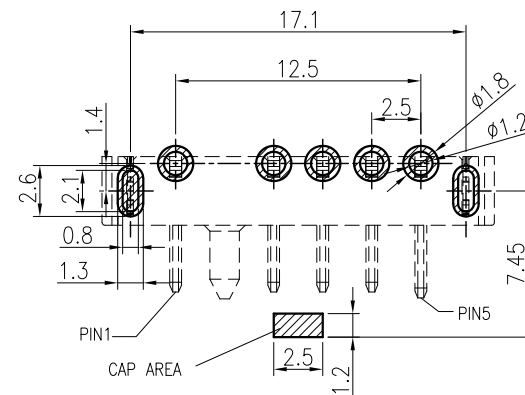
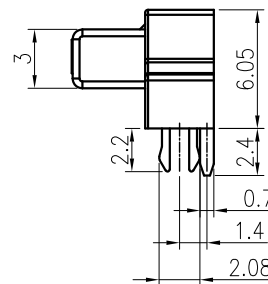
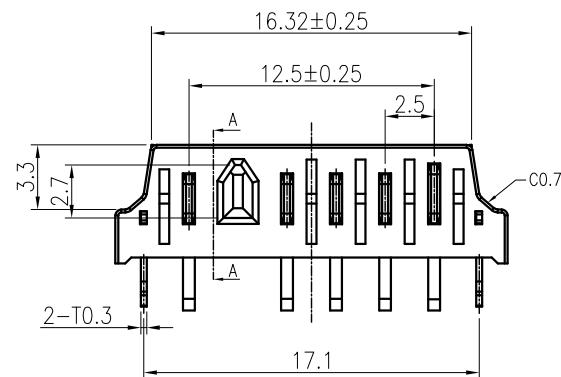
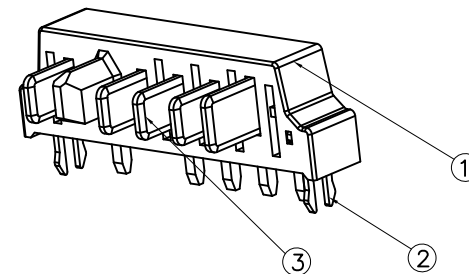
修订 REV	标记 MARK	修改摘要 REVISION DESCRIPTION	签名 SIGNATURE	日期 DATE
AO		NEW DWG		



0.8u" MIN GOLD PLATE IN CONTACT AREA/
100u" MIN MATTE TIN PLATE IN SOLDER
AREA OVER 50u" MIN NICKEL



SECTION A-A



P. C. B LAYOUT

- (1)Temperature: -40℃~105℃
(2)Relative humidity: 63% to 67%
(3)Rating: DC 25V 7A
(4)Contact Resistance:≤30m ohm
(5)Insulation Resistance:≥1000M ohm
(6)Withstand Voltage: AC 500V for 1min
(7)Soldering Temperature: 260±5℃ 5±0.5s



深圳市华德共创科技有限公司
Shenzhen Huade co-create Technology Co.,LTD
电话: 0755-27111216 传真: 0755-29940187

-TOLERANCES- UNLESS OTHERWISE SPECIFIED 公差参数表				TITLE: 产品名称: 2.5MM间距电池座			
X.X	±0.30	X.X*	±3°	APPD: 核准: 谢亮	PART NO: 产品编号: HDGC-2.5DS-5P		
X.XX	±0.30	X.XX*	±2°	CHECK: 校对: 王建业	DATE	SCALE	UNIT
X.XXX	±0.10	X.XXX*	±1°	DRAW: 绘图: 黄艳兰		1:1	mm
							A001